

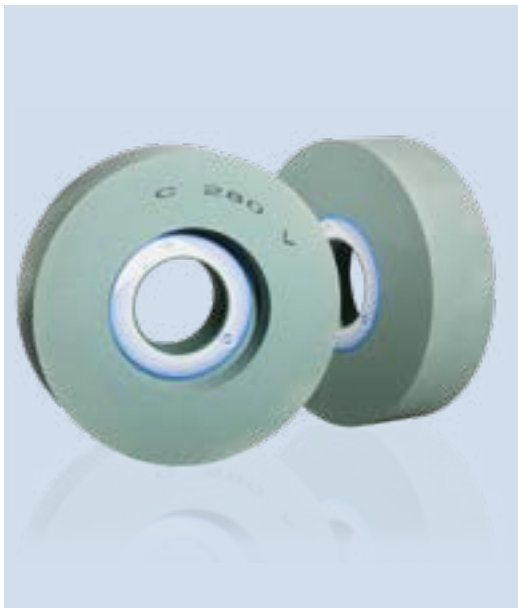


CERMIC

Vitrified bonded grinding wheels for fine grinding and for high-precision applications

Your Advantages

- Achieving very high surface qualities and demanding dimensional and shape tolerances thanks to ultra-fine grit sizes and ceramic bonding
- Consistently high profile accuracy with demanding radii
- Consistently high dimensional stability
- Individual tool specifications tailored to your process needs
- Efficient use for materials with crystallographic structures



	HERMES CERMIC	COMPETITION
Process data	$v_c = 50$ m/s; Material: HSS, hardened; Machine: Studer	
Surface quality	■■■■	■■■
Profile accuracy	■■■■	■■■
Chip removal rate	■■■	■■■



for an
excellent finish

CERMIC

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Application areas	<ul style="list-style-type: none">• High-precision applications: Grinding of injection nozzles, surgical instruments• Generation of high surface qualities in the $Rz < 1 \mu\text{m}$ range: grinding of dies, fine grinding of gear wheels• Grinding of sintered materials such as PM steel, hard metals, sintered materials
Grinding processes	All processes that require high surface qualities and have to meet demanding dimensional and shape tolerances
Bonding	Ceramic
Grain	Silicon carbide, aluminium oxide
Grit size	F 220 - F 500 Finer grain sizes possible by individual arrangement



PLEASE CONTACT US

Detailed information and literature for download
hermes-abrasives.com

You will find your direct contact person in the [Contacts](#) section.

HERMES Schleifmittel GmbH

Taskoepruestrasse 1 • 22761 Hamburg • Phone +49 40 8330-0 • Germany

